

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S67	1	11/003369	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/09 16:17
S68	2	("20050275048").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:18
S69	2	("6791660").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:19
S70	2	("4565928").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:20
S72	761	(257/E21.237,E21.484). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/09 16:22
S73	54335	(photoelectric (image adj1 sensor)) and (grind \$3 polish\$3 thin\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:52
S75	894	S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:53
S74	894	(photoelectric (image adj1 sensor)) and ((grind \$3 polish\$3 thin\$4) same ((glass dielectric) adj1 substrate)) and (glue adhesive (ultraviolet adj1 cured adj1 plastic) (epoxy adj1 resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:53

S77	2	((photoelectric (image adj1 sensor)) and ((grind \$3 polish\$3 thin\$4) same ((glass dielectric) adj1 substrate)) and (glue adhesive (ultraviolet adj1 cured adj1 plastic) (epoxy adj1 resin))).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:54
S76	1587	((photoelectric (image adj1 sensor)) and (grind \$3 polish\$3 thin\$4)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/15 12:54
S78	3070	((257/E21.237,E21.484) or (438/118,456)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/03 16:48
S83	12443	S80 and S81 and S82	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S82	269667	(photoelectric (image adj1 sensor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S81	3251696	(grind\$3 polish\$3 thin\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S80	524017	(dielectric insulat\$3 glass) near3 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S79	326450	(dielectric insulat\$3) near3 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:49
S84	306	(S80 and S81 and S82).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 16:50

S85	11	("4423435" "5501989" "5589694" "5744822" "5965064" "6461890" "6555917" "6624921" "6700133" "7071488"). PN. OR ("7180197"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/03 16:55
S86	2393	(257/777).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/03 17:29
L1	2025783	semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:41
L4	21920	(substrate near3 L2).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:44
L3	44801	(substrate with L2).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:44
L2	3251696	(grind\$3 polish\$3 thin\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:44
L7	1581	L6 and L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:46
L6	182465	L5.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:46
L5	1657229	(glue adhesive (ultraviolet adj1 cured adj1 plastic) (epoxy adj1 resin))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:46
L10	192	L9 and L7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:47

L9	139673	L8.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:47
L8	1900575	semiconductor adj chip integrated adj circuit IC	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 17:47
L11	39	("20030057359" "20030066311" "20040159902" "20050253213" "20050253213" "20050275048" "4565928" "5101099" "5270571" "5950074" "6429036" "6476469" "6528875" "6528875" "6737292" "6791660" "6958261" "6965107" "7109580" "7126210" "7141782").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:19
L14	130	L13 not L10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:27
L13	158	L12 and L6 and L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:27
L12	5925	(wafer near3 L2).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:27
L16	269667	(photoelectric (image adj1 sensor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:28
L19	499097	substrate.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:29
L18	30284	L16.clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:29

L21	442	(L19 L12) and L6 and L18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:30
L23	95	(wafer and L2 and L16). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:33
L22	18	(US-20060030074-\$ or US-20050266601-\$ or US- 20060033198-\$ or US- 20070166029-\$ or US- 20030056967-\$ or US- 20030049925-\$).did. or (US-5895233-\$ or US- 7029960-\$ or US- 6204506-\$ or US- 7229900-\$ or US- 5986736-\$ or US- 7180197-\$ or US- 7071488-\$ or US- 6624921-\$ or US- 6461890-\$ or US- 5965064-\$ or US- 6526653-\$ or US- 6483030-\$).did.	US-PGPUB; USPAT	OR	ON	2008/08/03 18:33
L25	11607	((438/118-119,455- 456,459,977,690- 693,700,959) or (257/ E21.237,E21.484)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/03 18:35
L26	11	("20040137723" "20040232104" "20060030074" "20060043555" "4565928" "5101099"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/03 18:38

8/3/2008 6:41:01 PM

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